



Product Change Notification / JAON-04TMOL584

Date:

01-Feb-2022

Product Category:

8-bit Microcontrollers, Analog Temperature Sensors, Analog to Digital Converters, Capacitive Touch Sensors, Charge Pump DC-to-DC Converters, Digital Potentiometers, Digital Temperature Sensors, Digital to Analog Converters, Instrumentation Amplifier, Interface- Controller Area Network (CAN), Interface- Infrared Products, Interface- LIN Transceiver, KEELOQ® Encoder Devices, Linear Comparators, Linear Op Amps, Linear Programmable Gain Amplifiers, Memory, Piezoelectric Horn Drivers and CO Detector, Power Management - System Supervisors/Voltage Detectors, Power MOSFET Drivers, Real-Time Clock/Calendar, RFID tag ICs - microID® ICs

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4539 Cancellation Notice: For the qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site

Affected CPNs:

[JAON-04TMOL584_Affected_CPN_02012022.pdf](#)

[JAON-04TMOL584_Affected_CPN_02012022.csv](#)

Notification Text:

PCN Status: Cancellation notification.

PCN Type: Manufacturing Change

Microchip Parts Affected: This change would have affected the selected products available in 8L SOIC package using 8390A die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: This qualification was originally performed to qualify a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

Impacts to Data Sheet: Not applicable

Change Impact: Not applicable

Reason for Change: Microchip has decided to not qualify a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

Change Implementation Status: Not applicable

Estimated Qualification Completion Date: Not applicable

Method to Identify Change: Not applicable

Revision History:

February 09, 2021: Issued initial notification.

February 01, 2022: Issued cancellation notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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If you wish to [change your PCN profile, including opt out](#), please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make

the applicable selections.

Affected Catalog Part Numbers (CPN)

24C00/SN
24C00-E/SN
24C00-I/SN
24C00T/SN
24C00T-I/SN
24C00T-E/SN
24LC00/SN
24AA00/SN
24LC00-I/SN
24AA00-I/SN
24LC00T/SN
24AA00T/SN
24LC00T-I/SN
24AA00T-I/SN
93LC46/SN
93LC46X/SN
93LC46B/SN
93LC46BX/SN
93LC46-I/SN
93LC46X-I/SN
93LC46B-I/SN
93LC46BX-I/SN
93AA46-I/SN
93AA46/SN
93LC46T/SN
93LC46XT/SN
93LC46BT/SN
93LC46BXT/SN
93AA46T/SN
93LC46T-I/SN
93LC46XT-I/SN
93LC46BT-I/SN
93LC46BXT-I/SN
93AA46T-I/SN
93LC56/SN
93LC56X/SN
93LC66/SN
93LC66X/SN
93AA66/SN
93AA66X/SN
93C56-E/SN
93C66-E/SN
93LC56-I/SN
93LC66-I/SN
93LC66X-I/SN
93AA56-I/SN

JAON-04TMOL584 - CCB 4539 Cancellation Notice: For the qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site

93AA66-I/SN
93AA56/SN
93LC56T/SN
93LC66T/SN
93AA56T/SN
93AA66T/SN
93AA66XT/SN
93LC56T-I/SN
93LC66T-I/SN
93LC66XT-I/SN
93AA56T-I/SN
93AA66T-I/SN
93C56T-E/SN
93C66T-E/SN
25LC080/SN
25AA080/SN
25C080/SN
25C080-E/SN
25LC080-I/SN
25AA080-I/SN
25C080-I/SN
25LC080T/SN
25AA080T/SN
25C080T/SN
25LC080T-I/SN
25AA080T-I/SN
25C080T-I/SN
25C080T-E/SN
25LC160/SN
25AA160/SN
25C160/SN
25C160-E/SN
25LC160-I/SN
25AA160-I/SN
25C160-I/SN
25LC160T/SN
25AA160T/SN
25C160T/SN
25LC160T-I/SN
25AA160T-I/SN
25C160T-I/SN
25C160T-E/SN
93LC76/SN
93AA76/SN
93C76-E/SN
93LC76-I/SN
93LC76T/SN
93AA76T/SN
93LC76T-I/SN

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93C761-E/SN

93LC86/SN

93AA86/SN

93C86-E/SN

93LC86-I/SN

93LC86T/SN

93AA86T/SN

93LC86T-I/SN

93C86T-E/SN

HCS300/SN042

HCS300/SN

HCS300-I/SN

HCS300T/SN031

HCS300T/SN

HCS300T-I/SN029

HCS300T-I/SN047

HCS300T-I/SN049

HCS300T-I/SN053

HCS300T-I/SN

HCS301/SN024

HCS301/SN

HCS301-I/SN

HCS301T/SN022

HCS301T/SN024

HCS301T/SN

HCS301T-I/SN028

HCS301T-I/SN029

HCS301T-I/SN

HCS200/SN

HCS200-I/SN

HCS200T/SN

HCS200T-I/SN

24LCS21A/SN

24LC21A/SN

24LC21/SN

24LC21A-I/SN100

24LCS21A-I/SN

24LC21A-I/SN

24LC21-I/SN

MCP6547T-I/SN

MCP6547T-E/SN

MCP6S21-I/SN

MCP6S21T-I/SN

MCP6S22-I/SN

24LC16BT/SNA31

24LC16BT/SNRVE

24LC16BT-I/SN

24LC16BT-I/SNRVE

24AA16T-I/SN

JAON-04TMOL584 - CCB 4539 Cancellation Notice: For the qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site

24LC16BT-E/SN

24LC16BT-E/SNA26

24AA01/SN

24AA01-I/SN

24AA01T/SN

24AA01T-I/SN

93AA46CT-I/SN

93AA46CXT-I/SN

93LC46CT-E/SN

93LC46CXT-E/SN

93LC56A/SN

93LC56B/SN

93LC56BX/SN

93LC56C-E/SN

93LC56CX-E/SN

93LC56A-E/SN

93LC56AX-E/SN

93LC56B-E/SN

93LC56BX-E/SN

93LC56C-I/SN

93LC56CX-I/SN

93AA56C-I/SN

24AA01H-I/SN

24LC01BHT-I/SN

24AA01HT-I/SN

24LC01BHT-E/SN

24LC02BH-E/SN

24AA02E48-E/SN

24AA02E64-E/SN

24LC02BH-I/SN100

24LC02BH-I/SN

24AA02H-I/SN

24AA02E48-I/SN

24AA02E64-I/SN

24AA02UID-I/SN

24LC02BHT-I/SN

24AA02HT-I/SN

24AA02E48T-I/SN

24AA02E64T-I/SN

24AA02UIDT-I/SN

24LC02BHT-E/SN

24AA02E48T-E/SN

24AA02E64T-E/SN

24LCS52/SN

24LCS52-I/SN

24AA52-I/SN

24LCS52T/SN

24LCS52T-I/SN

24AA52T-I/SN

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24LC024/SN

24LC025/SN

24VL024/SN

24VL025/SN

24LC024-E/SN

24LC025-E/SN

24LC024-I/SN

24AA024-I/SN

24LC025-I/SN

24AA025-I/SN

24LC024T/SN

24LC025T/SN

24VL024T/SN

24VL025T/SN

24LC024T-I/SN

24AA024T-I/SN

24LC025T-I/SN

24AA025T-I/SN

24LC024T-E/SN

24LC025T-E/SN

24VL014/SN

24LC014-E/SN

24LC014-I/SN

24AA014-I/SN

24VL014T/SN

24LC014T-I/SN

24AA014T-I/SN

24LC014T-E/SN

24C01C/SN

24C01C-E/SN

24C01C-I/SN

24C01CT/SN

24C01CT-I/SN

24C01CT-E/SN

24VL014H/SN

24LC014H-E/SN

24LC014H-I/SN

24AA014H-I/SN

24VL014HT/SN

24LC014HT-I/SN

24AA014HT-I/SN

24LC014HT-E/SN

24VL024H/SN

24LC024H-E/SN

24AA025E48-E/SN

24AA025E64-E/SN

24LC024H-I/SN

24AA024H-I/SN

24AA025E48-I/SN

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~~24AA025E64-I/SN~~

24AA025UID-I/SN

24VL024HT/SN

24LC024HT-I/SN

24AA024HT-I/SN

24AA025E48T-I/SN

24AA025E64T-I/SN

24AA025UIDT-I/SN

24LC024HT-E/SN

24AA025E48T-E/SN

24AA025E64T-E/SN

34VL02/SN

34LC02-E/SN

34AA02-E/SN

34LC02-I/SN

34AA02-I/SN

34VL02T/SN

34LC02T-I/SN

34AA02T-I/SN

34LC02T-E/SN

34AA02T-E/SN

MCP79410-I/SN

MCP79411-I/SN

MCP79412-I/SN

MCP79410T-I/SN

MCP79411T-I/SN

MCP79412T-I/SN

MCP79400-I/SN

MCP79401-I/SN

MCP79402-I/SN

MCP79400T-I/SN

MCP79401T-I/SN

MCP79402T-I/SN

MCP7940N-E/SN

MCP7940N-I/SN

MCP7940M-I/SN

MCP7940NT-I/SN

MCP7940MT-I/SN

MCP7940NT-E/SN

PIC12LF1552-E/SN

PIC12LF1552-I/SN

PIC12LF1552T-I/SN021

PIC12LF1552T-I/SN023

PIC12LF1552T-I/SN

25K512-I/SN

25A512-I/SN

25K512T-I/SN

25A512T-I/SN

PIC12F1822-E/SN

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PIC12F1822-E/SNC07

PIC12F1822-I/SN052

PIC12F1822-I/SN

PIC12F1822-I/SNC08

PIC12F1822-I/SNC11

PIC12F1822-I/SNC15

PIC12F1822T-I/SN039

PIC12F1822T-I/SN049

PIC12F1822T-I/SN052

PIC12F1822T-I/SN053

PIC12F1822T-I/SN

PIC12F1822T-I/SNC08

PIC12F1822T-I/SNC15

PIC12F1822T-E/SN046

PIC12F1822T-E/SN

PIC12F1822T-E/SNC07

PIC12LF1822-E/SN

PIC12LF1822-I/SN

PIC12LF1822T-I/SN

PIC12LF1822T-E/SN

PIC12F1840-E/SN

PIC12F1840-I/SN

PIC12F1840T-I/SN

PIC12F1840T-E/SN

93LC86B-I/SN

93AA86B-I/SN

93LC86AT-I/SN

93AA86AT-I/SN

93LC86BT-I/SN

93AA86BT-I/SN

93LC86AT-E/SN

93LC86BT-E/SN

93C76A-E/SN

93C76B-E/SN

93C76A-I/SN

93C76B-I/SN

93C76AT-I/SN

93C76BT-I/SN

93C76AT-E/SN

93C76BT-E/SN

93C86A-E/SN

93C86B-E/SN

93C86A-I/SN

93C86B-I/SN

93C86AT-I/SN

93C86BT-I/SN

93C86AT-E/SN

93C86BT-E/SN

MCP4021-202E/SN

JAON-04TMOL584 - CCB 4539 Cancellation Notice: For the qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site

MCP4021-502E/SN
MCP4021-103E/SN
MCP4021-503E/SN
MCP4021T-202E/SN
MCP4021T-502E/SN
MCP4021T-103E/SN
MCP4021T-503E/SN
MCP4011-202E/SN
MCP4011-502E/SN
MCP4011-103E/SN
MCP4011-503E/SN
MCP4011T-202E/SN
MCP4011T-502E/SN
MCP4011T-103E/SN
MCP4011T-503E/SN
25LC256-E/SN
25AA256-E/SN
25LC256-I/SN
25LC256-I/SNRVB
25AA256-I/SN
25LC256-H/SN
25LC256T-H/SN
25LC256T-I/SN
25LC256T-I/SNRVB
25AA256T-I/SN
25AA256T-I/SNB31
25LC256T-E/SN
25AA256T-E/SN
25LC320A-E/SN
25LC320A-I/SN
25AA320A-I/SN
25AA320A-I/SNB22
25LC320A-H/SN
25LC320AT-H/SN
25LC320AT-I/SN
25AA320AT-I/SN
25AA320AT-I/SNB22
25LC320AT-E/SN
25LC160D-E/SN
25AA160D-E/SN
25LC160D-I/SN
25AA160D-I/SN
25LC160D-H/SN
25LC160DT-H/SN
25LC160DT-I/SN
25AA160DT-I/SN
MCP6285-E/SN
MCP6295-E/SN
MCP6275T-E/SN

JAON-04TMOL584 - CCB 4539 Cancellation Notice: For the qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site

MCP6285T-E/SN

MCP6295T-E/SN

MCP6L72T-E/SN

MCP6271-E/SN

MCP6273-E/SN

MCP6281-E/SN

MCP6283-E/SN

MCP6291-E/SN

MCP6293-E/SN

MCP6271T-E/SN

MCP6273T-E/SN

MCP6281T-E/SN

MCP6283T-E/SN

MCP6291T-E/SN

MCP6293T-E/SN

MCP6L71T-E/SN

MCP6L91T-E/SN

MCP6031-E/SN

MCP6033-E/SN

MCP6031T-E/SN

MCP6033T-E/SN

MCP6032-E/SN

24LC02BT-E/SN

24LC04B/SN

24AA04/SN

24LC04B-E/SN

24AA04-I/SN

24LC04BT/SN

24AA04T/SN

24AA04T-I/SN

24AA04T-I/SNB24

24LC04BT-E/SN

24LC32A/SN

24LC32A-E/SN

24LC32A-I/SN

24LC32A-I/SNA27

24LC32A-I/SNRVE

24AA32A-I/SN

24AA32A-I/SNRVE

34A47F-I/SN

24LC32AT/SN

24LC32AT-I/SN

24LC32AT-I/SNA23

24LC32AT-I/SNA27

24LC32AT-I/SNRVE

24AA32AT-I/SN

24AA32AT-I/SNRVE

34A47FT-I/SN

24LC32AT-E/SN

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PIC12F629-C/SN

PIC12F629-E/SN244

PIC12F629-E/SN

PIC12F629-I/SN102

PIC12F629-I/SN148

PIC12F629-I/SN206

PIC12F629-I/SN207

PIC12F629-I/SN208

PIC12F629-I/SN209

PIC12F629-I/SN

HA688-I/SN

PIC12F629-I/SNC24

PIC12F629T-C/SN

PIC12F629T-I/SN039

PIC12F629T-I/SN065

PIC12F629T-I/SN069

PIC12F629T-I/SN084

PIC12F629T-I/SN091

PIC12F629T-I/SN102

PIC12F629T-I/SN138

PIC12F629T-I/SN148

PIC12F629T-I/SN211

PIC12F629T-I/SN213

PIC12F629T-I/SN214

PIC12F629T-I/SN220

PIC12F629T-I/SN232

PIC12F629T-I/SN233

PIC12F629T-I/SN241

PIC12F629T-I/SN242

PIC12F629T-I/SN245

PIC12F629T-I/SN247

PIC12F629T-I/SN248

PIC12F629T-I/SN249

PIC12F629T-I/SN250

PIC12F629T-I/SN

PIC12F629T-I/SNC19

PIC12F629T-E/SN244

PIC12F629T-E/SN246

PIC12F629T-E/SN

25LC160B-E/SN

25LC160B-I/SN

25AA160B-I/SN

25LC160BT-I/SN

25AA160BT-I/SN

25LC160BT-E/SN

25LC080B-E/SN

25LC080B-I/SN

25AA080B-I/SN

25LC080BT-I/SN

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25AA080BT-I/SN

25AA080BT-I/SNB21

25LC080BT-E/SN

25LC080A-E/SN

25LC080A-I/SN

25AA080A-I/SN

25LC080A-H/SN

25LC080AT-H/SN

25LC080AT-I/SN

25AA080AT-I/SN

25LC080AT-E/SN

25LC160A-E/SN

25AA160A-I/SN103

25LC160A-I/SN

25AA160A-I/SN

25AA160AT-I/SN103

25LC160AT-I/SN

25LC160AT-I/SNA79

25AA160AT-I/SN

25LC160AT-E/SN

93LC46A/SN

93LC46AX/SN

93LC46A-E/SN

93LC46AX-E/SN

93LC46A-I/SN

93LC46AX-I/SN

93AA46A-I/SN

93AA46AX-I/SN

93AA46AE48-I/SN

93LC46AT/SN

93LC46AXT/SN

93LC46AT-I/SN

93LC46AXT-I/SN

93AA46AT-I/SN

93AA46AXT-I/SN

93AA46AE48T-I/SN

93LC46AT-E/SN

93LC46AXT-E/SN

93LC46B-E/SN

93LC46BX-E/SN

93LC76BT-I/SN

93AA76BT-I/SN

93LC76AT-E/SN

93LC76BT-E/SN

93LC86A-E/SN

93LC86B-E/SN

93LC86A-I/SN

93AA86A-I/SN

MCP602-I/SNREL

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MCP602T-I/SN

MCP602T-E/SN

MCP6L2T-E/SN

MCP41050-E/SN

MCP41050-I/SN

MCP41050T-I/SN

MCP41050T-E/SN

MCP41100-E/SN

MCP41100-I/SN

MCP41100T-I/SN

MCP41100T-E/SN

MCP3301-BI/SN

MCP3301-CI/SN

MCP3301T-BI/SN

MCP3301T-CI/SN

MCP6042-E/SN

MCP6042-I/SN

MCP6042-I/SNREL

MCP6042T-I/SN

MCP6042T-E/SN

MCP6142-E/SN

MCP6142-I/SN

MCP6142T-I/SN

MCP6142T-E/SN

PIC12F675T-I/SN179

PIC12F675T-I/SN185

PIC12F675T-I/SN190

PIC12F675T-I/SN191

PIC12F675T-I/SN194

PIC12F675T-I/SN195

PIC12F675T-I/SN199

PIC12F675T-I/SN200

PIC12F675T-I/SN201

PIC12F675T-I/SN202

PIC12F675T-I/SN206

PIC12F675T-I/SN207

PIC12F675T-I/SN208

PIC12F675T-I/SN

PIC12F675T-I/SNC15

PIC12F675T-E/SN073

PIC12F675T-E/SN082

PIC12F675T-E/SN091

PIC12F675T-E/SN

24LC256-E/SN

24LC256-I/SN

24LC256-I/SNRVE

24AA256-I/SN

24AA256-I/SNRVE

24LC256-I/SNREL

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24LC256T-I/SN

24LC256T-I/SNRVE

24AA256T-I/SN

24AA256T-I/SNRVE

24LC256T-E/SN

24LC256T-E/SNRVE

24FC256-I/SN

24FC256T-I/SN

24LC128-E/SN

24LC128-I/SN

24LC128-I/SNRVE

24AA128-I/SN

24LC128T-I/SN

24LC128T-I/SNRVE

24AA128T-I/SN

24LC128T-E/SN

24FC128-I/SN

24FC128-I/SNRVE

24FC128T-I/SN

24FC128T-I/SNRVE

24AA64/SN

24LC64-E/SN

24LC64-I/SN

24AA64-I/SN

24LC64-I/SNRVE

24AA64T/SN

24LC64T-I/SN

24LC64T-I/SNA22

24AA64T-I/SN

34A83GT-I/SN

24LC64T-I/SNRVE

24LC64T-E/SN

24LC16B-I/SN

24AA16-I/SN

24AA16-I/SNB22

24LC16BT/SN

MCP6482-E/SN

MCP6492-E/SN

MCP6472-E/SN

MCP6482T-E/SN

MCP6492T-E/SN

MCP6472T-E/SN

MCP6422-E/SN

MCP6422T-E/SN

34AA04-E/SN

34AA04-I/SN

34AA04T-I/SN

34AA04T-E/SN

24AA044-E/SN

JAON-04TMOL584 - CCB 4539 Cancellation Notice: For the qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site

~~24AA044-I/SN~~

24AA044T-I/SN

24AA044T-E/SN

11LC010-E/SN

11LC010-I/SN

11AA010-I/SN

11LC010T-I/SN

11AA010T-I/SN

11LC010T-E/SN

11LC020-E/SN

11LC020-I/SN

11AA020-I/SN

11AA02E48-I/SN

11AA02E64-I/SN

11AA02UID-I/SN

11LC020T-I/SN

11AA020T-I/SN

11AA02E48T-I/SN

11AA02E64T-I/SN

11AA02UIDT-I/SN

11LC020T-E/SN

11LC040-E/SN

11LC040-I/SN

11AA040-I/SN

11LC040T-I/SN

11AA040T-I/SN

11LC040T-E/SN

11LC080-E/SN

11LC080-I/SN

11AA080-I/SN

11LC080T-I/SN

11AA080T-I/SN

11LC080T-E/SN

11LC160-E/SN

11LC160-I/SN

11AA160-I/SN

11LC160T-I/SN

11AA160T-I/SN

11LC160T-E/SN

11LC161-E/SN

11LC161-I/SN

11AA161-I/SN

11LC161T-I/SN

11AA161T-I/SN

11LC161T-E/SN

24AA02/SNB79

24LC02B-I/SNA32

24LC02BT-I/SN104

24LC02BT-I/SNA32

JAON-04TMOL584 - CCB 4539 Cancellation Notice: For the qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site

24LC01BH-E/SN

24LC01BH-I/SN

MCP4151T-104E/SN

MCP4151T-503E/SN

MCP4161T-502E/SN

MCP4161T-103E/SN

MCP4161T-104E/SN

MCP4161T-503E/SN

MCP4132T-502E/SN

MCP4132T-103E/SN

MCP4132T-104E/SN

MCP4132T-503E/SN

MCP4142T-502E/SN

MCP4142T-103E/SN

MCP4142T-104E/SN

MCP4142T-503E/SN

MCP4152T-502E/SN

MCP4152T-103E/SN

MCP4152T-104E/SN

MCP4152T-503E/SN

MCP4162T-502E/SN

MCP4162T-103E/SN

MCP4162T-104E/SN

MCP4162T-503E/SN

25LC128-E/SN

25AA128-E/SN

25LC128-I/SN

25AA128-I/SN

25LC128-H/SN

25LC128T-H/SN

25LC128T-I/SN

25AA128T-I/SN

25AA128T-I/SNRVA

25LC128T-E/SN

25LC128T-E/SNRVA

25AA128T-E/SN

25LC640A-E/SN

25AA640A-E/SN

25LC640A-M/SN

25LC640A-I/SN

25AA640A-I/SN

25LC640A-H/SN

25LC640AT-H/SN

25LC640AT-I/SN

25AA640AT-I/SN

25AA640AT-I/SNB23

25LC640AT-M/SN

25LC640AT-E/SN

25AA640AT-E/SN

JAON-04TMOL584 - CCB 4539 Cancellation Notice: For the qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site

PIC12F683-E/SN084

PIC12F683-E/SN

PIC12F683-I/SN075

PIC12F683-I/SN

PIC12F683T-I/SN072

PIC12F683T-I/SN091

PIC12F683T-I/SN

PIC12F683T-E/SN084

PIC12F683T-E/SN092

PIC12F683T-E/SN098

PIC12F683T-E/SN

PIC12F635-E/SN

PIC12F635-I/SN057

PIC12F635-I/SN

PIC12F635T-I/SN050

PIC12F635T-I/SN058

PIC12F635T-I/SN

PIC12F510-E/SN

PIC12F510-I/SN

PIC12F510-I/SNC06

MCV08A-I/SN

PIC12F510T-I/SN026

PIC12F510T-I/SN041

PIC12F510T-I/SN058

PIC12F510T-I/SN064

PIC12F510T-I/SN065

PIC12F510T-I/SN073

PIC12F510T-I/SN074

PIC12F510T-I/SN075

PIC12F510T-I/SN077

PIC12F510T-I/SN078

PIC12F510T-I/SN079

PIC12F510T-I/SN

PIC12F510T-E/SN070

PIC12F510T-E/SN

PIC12F519-E/SN

PIC12F519-I/SN039

PIC12F519-I/SN041

PIC12F519-I/SN

PIC12F519T-I/SN025

PIC12F519T-I/SN029

PIC12F519T-I/SN030

PIC12F519T-I/SN031

PIC12F519T-I/SN033

PIC12F519T-I/SN035

PIC12F519T-I/SN037

PIC12F519T-I/SN039

PIC12F519T-I/SN040

PIC12F519T-I/SN041

JAON-04TMOL584 - CCB 4539 Cancellation Notice: For the qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site

PIC12F519T-I/SN042
PIC12F519T-I/SN044
PIC12F519T-I/SN047
PIC12F519T-I/SN048
PIC12F519T-I/SN
PIC12F519T-E/SN
PIC12F617-E/SN020
PIC12F617-E/SN031
PIC12F617-E/SN033
PIC12F617-E/SN034
PIC12F617-E/SN
PIC12F617-I/SN030
PIC12F617-I/SN032
PIC12F617-I/SN053
PIC12F617-I/SN
PIC12F617-I/SNC15
PIC12F617T-I/SN022
PIC12F617T-I/SN028
PIC12F617T-I/SN030
PIC12F617T-I/SN032
MCP14E6-E/SN
MCP14E6T-E/SN
MCP14E7-E/SN
MCP14E7T-E/SN
MCP14E8-E/SN
MCP14E8T-E/SN
MCP14E9-E/SN
MCP14E9T-E/SN
MCP14E10-E/SN
MCP14E10T-E/SN
MCP14E11-E/SN
MCP14E11T-E/SN
25LC040/SN
25C040/SN
25C040-E/SN
25LC040-I/SN
25AA040-I/SN
25C040-I/SN
25LC040T/SN
25C040T/SN
25LC040T-I/SN
25AA040T-I/SN
25C040T-I/SN
25C040T-E/SN
93LC46BT-I/SNRVA
93C66B-I/SN
93C66BT-I/SN
93AA56CX-I/SN
93LC56A-I/SN

JAON-04TMOL584 - CCB 4539 Cancellation Notice: For the qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site

93LC56AX-I/SN
93AA56A-I/SN
93AA56AX-I/SN
93LC56B-I/SN
93LC56BX-I/SN
93AA56B-I/SN
93AA56BX-I/SN
93LC56AT/SN
93LC56BT/SN
93LC56BXT/SN
93LC56CT-I/SN
93LC56CXT-I/SN
93AA56CT-I/SN
93AA56CXT-I/SN
93LC56AT-I/SN
93LC56AXT-I/SN
93AA56AT-I/SN
93AA56AXT-I/SN
93LC56BT-I/SN
93LC56BXT-I/SN
93AA56BT-I/SN
93AA56BXT-I/SN
93LC56CT-E/SN
93LC56CXT-E/SN
93LC56AT-E/SN
93LC56AXT-E/SN
93LC56BT-E/SN
93LC56BXT-E/SN
93LC66A/SN
93LC66AX/SN
93LC66B/SN
93LC66BX/SN
93LC66C-E/SN
93LC66CX-E/SN
93LC66A-E/SN
93LC66AX-E/SN
93LC66B-E/SN
93LC66BX-E/SN
93LC66C-I/SN
93LC66CX-I/SN
93AA66C-I/SN
93AA66CX-I/SN
93LC66A-I/SN
93LC66AX-I/SN
93AA66A-I/SN
93AA66AX-I/SN
93LC66B-I/SN
93LC66B-I/SN15K
93LC66BX-I/SN

JAON-04TMOL584 - CCB 4539 Cancellation Notice: For the qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site

~~93AA66B-I/SN~~

93AA66BX-I/SN

93LC66AT/SN

93LC66BT/SN

93LC66CT-I/SN

93LC66CXT-I/SN

93AA66CT-I/SN

93AA66CXT-I/SN

93LC66AT-I/SN

93LC66AXT-I/SN

93AA66AT-I/SN

93AA66AXT-I/SN

93LC66BT-I/SN

93LC66BT-I/SN15K

93LC66BXT-I/SN

93AA66BT-I/SN

93AA66BXT-I/SN

93LC66CT-E/SN

93LC66CXT-E/SN

93LC66AT-E/SN

93LC66AXT-E/SN

93LC66BT-E/SN

93LC66BXT-E/SN

93C46C-E/SN

93C46C-I/SN

93C46CT-I/SN

93C46CT-E/SN

93C56C-E/SN

93C56A-E/SN

93C56B-E/SN

93C56C-I/SN

93C56A-I/SN

93C56B-I/SN

93C56CT-I/SN

93C56AT-I/SN

93C56BT-I/SN

93C56CT-E/SN

93C56AT-E/SN

93C56BT-E/SN

93C66C-E/SN

93C66A-E/SN

93C66B-E/SN

93C66C-I/SN

93C66A-I/SN

93C66CT-I/SN

93C66AT-I/SN

93C66CT-E/SN

93C66AT-E/SN

93C66BT-E/SN

JAON-04TMOL584 - CCB 4539 Cancellation Notice: For the qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site

MCP2122-E/SN

MCP2122T-E/SN

93LC76C-E/SN

93LC76C-I/SN

93AA76C-I/SN

93LC76CT-I/SN

93AA76CT-I/SN

93LC76CT-E/SN

93LC86C-E/SN

93LC86C-I/SN

93AA86C-I/SN

93LC86CT-I/SN

93AA86CT-I/SN

93LC86CT-E/SN

93C76C-E/SN

93C76C-I/SN

93C76CT-I/SN

93C76CT-E/SN

93C86C-E/SN

93C86C-I/SN

93C86CT-I/SN

93C86CT-E/SN

93LC76A-E/SN

93LC76B-E/SN

93LC76A-I/SN

93AA76A-I/SN

93LC76B-I/SN

93AA76B-I/SN

93LC76AT-I/SN

93AA76AT-I/SN

25LC512T-M/SN

25LC512T-E/SN

25AA512-I/SN

25AA512T-I/SN

25AA512T-I/SN-SCI

MCP3422A0-E/SN

MCP3426A0-E/SN

MCP3422A0T-E/SN

MCP3426A0T-E/SN

MCP3422A1-E/SN

MCP3426A1-E/SN

MCP3422A1T-E/SN

MCP3426A1T-E/SN

MCP3422A2-E/SN

MCP3426A2-E/SN

MCP3422A2T-E/SN

MCP3426A2T-E/SN

MCP3422A3-E/SN

MCP3426A3-E/SN

JAON-04TMOL584 - CCB 4539 Cancellation Notice: For the qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site

MCP3422A3T-E/SN

MCP3426A3T-E/SN

MCP3422A4-E/SN

MCP3426A4-E/SN

MCP3422A4T-E/SN

MCP3426A4T-E/SN

MCP3422A5-E/SN

MCP3426A5-E/SN

MCP6546-E/SN

MCP6548-E/SN

MCP6546-I/SN

MCP6548-I/SN

MCP6546T-I/SN

MCP6548T-I/SN

MCP6546T-E/SN

MCP6548T-E/SN

MCP6547-E/SN

MCP6547-I/SN

MCP6002-E/SN

MCP6002-I/SN

MCP6002T-I/SN

MCP6002T-E/SN

MCP6L02T-E/SN

MCP6231-E/SN

MCP6231T-E/SN

MCP6241-E/SN

MCP6241T-E/SN

MCP6232-E/SN

MCP6232T-E/SN

MCP6242-E/SN

MCP6242T-E/SN

MCP6S91-E/SN

MCP6S91T-E/SN

MCP6S92-E/SN

MCP6S92T-E/SN

MCP6G01-E/SN

MCP6G01T-E/SN

MCP6G03-E/SN

MCP6G03T-E/SN

MCP6G02-E/SN

MCP6G02T-E/SN

MCP6041-E/SN

MCP6043-E/SN

MCP6041-I/SN

MCP6043-I/SN

MCP6041T-I/SN

MCP6043T-I/SN

MCP6041T-E/SN

MCP6043T-E/SN

JAON-04TMOL584 - CCB 4539 Cancellation Notice: For the qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site

MCP6141-E/SN

MCP6143-E/SN

MCP6141-I/SN

MCP6143-I/SN

MCP6141T-I/SN

MCP6143T-I/SN

MCP6141T-E/SN

MCP6143T-E/SN

MCP6402-E/SN

MCP6402-H/SN

MCP6407T-H/SN

MCP6407-H/SN

MCP6402T-H/SN

MCP6402T-E/SN

MCP6442-E/SN

MCP6442T-E/SN

24LC01B/SN

24LC01B-E/SN

24LC01B-I/SN

24LC01BT/SN

24LC01BT-I/SN

24LC01BT-I/SNA21

24LC01BT-I/SNA23

24LC01BT-I/SNRVE

24LC01BT-E/SN

24LC04B-I/SN

24LC04BT-I/SN

24LC04BT-I/SNA29

24LC64-I/SNRVA

24LC64T-I/SNRVA

25LC640-E/SN

25LC640-I/SN

25AA640-I/SN

25LC640T-I/SN

25AA640T-I/SN

25LC640T-E/SN

25LC320/SN

25C320/SN

25LC320-E/SN

25C320-E/SN

25LC320-I/SN

25AA320-I/SN

25C320-I/SN

25LC320T/SN

25C320T/SN

25LC320T-I/SN

25AA320T-I/SN

25C320T-I/SN

25LC320T-E/SN

JAON-04TMOL584 - CCB 4539 Cancellation Notice: For the qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site

25C3201-E/SN

HCS201/SN

HCS201-I/SN036

HCS201-I/SN

HCS201T/SN017

HCS201T/SN021

HCS201T/SN024

HCS201T/SN

HCS201T-I/SN

HCS101-I/SN

24C02C/SN

24C02C-E/SN

24C02C-I/SN

24C02CT/SN

24C02CT-I/SN

24C02CT-E/SN

MCRF450X/SN

MCRF450TX/SN

PIC12F675-C/SN

PIC12F675-E/SN

PIC12F675-I/SN102

PIC12F675-I/SN112

PIC12F675-I/SN166

PIC12F675-I/SN172

PIC12F675-I/SN177

PIC12F675-I/SN202

PIC12F675-I/SN

PIC12F675-I/SNC15

PIC12F675T-C/SN

PIC12F675T-I/SN026

PIC12F675T-I/SN049

PIC12F675T-I/SN075

PIC12F675T-I/SN079

PIC12F675T-I/SN085

PIC12F675T-I/SN121

PIC12F675T-I/SN131

PIC12F675T-I/SN145

PIC12F675T-I/SN150

PIC12F675T-I/SN152

PIC12F675T-I/SN153

PIC12F675T-I/SN166

PIC12F675T-I/SN172

PIC12F675T-I/SN173

PIC12F675T-I/SN178

24LC08B/SN

24AA08/SN

24LC08B-E/SN

24LC08B-I/SNRVE

24LC08B-I/SNA27

JAON-04TMOL584 - CCB 4539 Cancellation Notice: For the qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site

24AA08-I/SN

24LC08BT/SNRVE

24AA08T/SN

24LC08BT-I/SNRVE

24LC08BT-I/SNA23

24LC08BT-I/SNA27

24AA08T-I/SN

24LC08BT-E/SN

24LC08B-I/SN

24LC08BT/SN

24LC08BT-I/SN

24LC16B/SN

24LC16B-E/SN

24LC16B-E/SNA26

MCP6275-E/SN

25LC160DT-E/SN

25LC160DT-E/SN16KA21

25AA160DT-E/SN

25LC080D-E/SN

25LC080D-I/SN

25AA080D-I/SN

25LC080D-H/SN

25LC080DT-H/SN

25LC080DT-I/SN

25AA080DT-I/SN

25AA080DT-I/SN-SCI

25LC080DT-E/SN

25LC160C-E/SN

25LC160C-I/SN

25AA160C-I/SN

25LC160C-H/SN

25LC160CT-H/SN

25LC160CT-I/SN

25AA160CT-I/SN

25LC160CT-E/SN

25LC080C-E/SN

25LC080C-I/SN

25AA080C-I/SN

25LC080C-H/SN

25LC080CT-H/SN

25LC080CT-I/SN

25AA080CT-I/SN

25LC080CT-E/SN

MCP4131-502E/SN

MCP4131-103E/SN

MCP4131-104E/SN

MCP4131-503E/SN

MCP4141-502E/SN

MCP4141-103E/SN

JAON-04TMOL584 - CCB 4539 Cancellation Notice: For the qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site

MCP4141-104E/SN
MCP4141-503E/SN
MCP4151-502E/SN
MCP4151-103E/SN
MCP4151-104E/SN
MCP4151-503E/SN
MCP4161-502E/SN
MCP4161-103E/SN
MCP4161-104E/SN
MCP4161-503E/SN
MCP4132-502E/SN
MCP4132-103E/SN
MCP4132-104E/SN
MCP4132-503E/SN
MCP4142-502E/SN
MCP4142-103E/SN
MCP4142-104E/SN
MCP4142-503E/SN
MCP4152-502E/SN
MCP4152-103E/SN
MCP4152-104E/SN
MCP4152-503E/SN
MCP4162-502E/SN
MCP4162-103E/SN
MCP4162-104E/SN
MCP4162-503E/SN
MCP4131T-502E/SN
MCP4131T-103E/SN
MCP4131T-104E/SN
MCP4131T-503E/SN
MCP4141T-502E/SN
MCP4141T-103E/SN
MCP4141T-104E/SN
MCP4141T-503E/SN
MCP4151T-502E/SN
MCP4151T-103E/SN
PIC12F617T-I/SN038
PIC12F617T-I/SN044
PIC12F617T-I/SN053
PIC12F617T-I/SN059
PIC12F617T-I/SN
PIC12F617T-I/SNC15
PIC12F617T-E/SN020
PIC12F617T-E/SN024
PIC12F617T-E/SN026
PIC12F617T-E/SN027
PIC12F617T-E/SN031
PIC12F617T-E/SN033
PIC12F617T-E/SN034

JAON-04TMOL584 - CCB 4539 Cancellation Notice: For the qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site

PIC12F617T-E/SN036
PIC12F617T-E/SN037
PIC12F617T-E/SN050
PIC12F617T-E/SN051
PIC12F617T-E/SN052
PIC12F617T-E/SN055
PIC12F617T-E/SN067
PIC12F617T-E/SN071
PIC12F617T-E/SN
TCN75AVOA
MCP9801-M/SN
MCP9801-M/SNRC2
MCP9801T-M/SN
MCP9801T-M/SNRC2
TCN75AVOA713
MCP9803-M/SN
MCP9803-M/SNRC2
MCP9803T-M/SN
MCP9803T-M/SNRC2
MCP3550-50E/SN
MCP3550-60E/SN
MCP3550T-50E/SN
MCP3550T-60E/SN
MCP3551-E/SN
MCP3551T-E/SN
MCP3553-E/SN
MCP3553T-E/SN
MCP4822-E/SN
MCP4802-E/SN
MCP4812-E/SN
MCP4822T-E/SN
MCP4802T-E/SN
MCP4812T-E/SN
PIC12F508-E/SN
PIC12F508-I/SN038
PIC12F508-I/SN080
PIC12F508-I/SN
HA1100/SN
PIC12F508T-I/SN020
PIC12F508T-I/SN025
PIC12F508T-I/SN040
PIC12F508T-I/SN045
PIC12F508T-I/SN056
PIC12F508T-I/SN066
PIC12F508T-I/SN080
PIC12F508T-I/SN
PIC12F508T-E/SN079
PIC12F508T-E/SN
PIC12F509-E/SN055

JAON-04TMOL584 - CCB 4539 Cancellation Notice: For the qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site

PIC12F509-E/SN

PIC12F509-I/SN051

PIC12F509-I/SN

PIC12F509T-I/SN047

PIC12F509T-I/SN048

PIC12F509T-I/SN051

PIC12F509T-I/SN058

PIC12F509T-I/SN

PIC12F509T-E/SN052

PIC12F509T-E/SN055

PIC12F509T-E/SN

25LC010A-E/SN

25LC010A-I/SN

25AA010A-I/SN

25LC010A-H/SN

25LC010AT-H/SN

25LC010AT-I/SN

25AA010AT-I/SN

25LC010AT-E/SN

25LC020A-E/SN

25LC020A-I/SN

25AA020A-I/SN

25AA02E48-I/SN

25AA02E64-I/SN

25AA02UID-I/SN

25LC020A-H/SN

25LC020AT-H/SN

25LC020AT-I/SN

25AA020AT-I/SN

25AA02E48T-I/SN

25AA02E64T-I/SN

25AA02UIDT-I/SN

25LC020AT-E/SN

25LC040A-E/SN

25LC040A-M/SN

25LC040A-I/SN103

25LC040A-I/SN

25AA040A-I/SN

25LC040A-H/SN

25LC040AT-H/SN

25LC040AT-I/SN103

25LC040AT-I/SN

25AA040AT-I/SN

25LC040AT-M/SN

25LC040AT-E/SN

PIC12F615-E/SN

PIC12F615-I/SN083

PIC12F615-I/SN

PIC12F615-H/SN

JAON-04TMOL584 - CCB 4539 Cancellation Notice: For the qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site

PIC12F615T-I/SN020

PIC12F615T-I/SN043

PIC12F615T-I/SN051

PIC12F615T-I/SN057

PIC12F615T-I/SN058

PIC12F615T-I/SN071

PIC12F615T-I/SN076

PIC12F615T-I/SN079

PIC12F615T-I/SN083

PIC12F615T-I/SN

PIC12F615T-E/SN

PIC12HV615-E/SN

PIC12HV615-I/SN

PIC12HV615T-I/SN022

PIC12HV615T-I/SN

PIC12HV615T-E/SN035

PIC12HV615T-E/SN043

PIC12HV615T-E/SN044

PIC12HV615T-E/SN

PIC12F609-E/SN

PIC12F609-I/SN

PIC12F609T-I/SN027

PIC12F609T-I/SN

PIC12F609T-E/SN

PIC12HV609-E/SN

PIC12HV609-I/SN

PIC12HV609T-I/SN

25LC512-E/SN

25LC512-M/SN

25LC512-I/SN

25LC512T-I/SN

MCP3422A5T-E/SN

MCP3426A5T-E/SN

MCP3422A6-E/SN

MCP3426A6-E/SN

MCP3422A6T-E/SN

MCP3426A6T-E/SN

MCP3422A7-E/SN

MCP3426A7-E/SN

MCP3422A7T-E/SN

MCP3426A7T-E/SN

24LC08BH-E/SN

24LC08BH-I/SN

24AA08H-I/SN

24LC08BHT-I/SN

24AA08HT-I/SN

24LC08BHT-E/SN

24AA16-E/SN

24LC16B-M/SN

JAON-04TMOL584 - CCB 4539 Cancellation Notice: For the qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site

24LC16BT-I/SNA79

24AA16T-I/SNB22

24LC16BT-M/SN

24AA16T-E/SN

24LC16BH-E/SN

24LC16BH-I/SN

24AA16H-I/SN

24LC16BHT-I/SN

24AA16HT-I/SN

24LC16BHT-E/SN

24AA32AT-I/SNB79

24LC32AF-E/SN

24LC32AF-I/SN

24AA32AF-I/SN

24LC32AFT-I/SN

24AA32AFT-I/SN

24LC32AFT-E/SN

24AA64-E/SN

24LC64-I/SN100

24AA64-I/SN101

24FC64-I/SN

24LC64T-I/SN100

24AA64T-I/SN101

24LC64T-I/SNA79

24AA64T-I/SNB79

24FC64T-I/SN

24LC64T-E/SNA31

24AA64T-E/SN

24LC64F-E/SN

24LC64F-I/SN

24AA64F-I/SN

24FC64F-I/SN

24LC64FT-I/SN

24AA64FT-I/SN

24FC64FT-I/SN

24LC64FT-E/SN

24FC128-E/SN

24LC128-I/SNRVF

24LC128T-I/SNRVF

24AA128T-I/SNRVF

24FC128T-E/SN

24LC04BT-I/SNA79

24LC04BH-E/SN

24LC04BH-I/SN

24AA04H-I/SN

24LC04BHT-I/SN

24AA04HT-I/SN

24LC04BHT-E/SN

24LC512-E/SN

JAON-04TMOL584 - CCB 4539 Cancellation Notice: For the qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site

24LC512-I/SN

24AA512-I/SN

24FC512-I/SN

24FC512-I/SNC79

24FC512T-I/SN101

24LC512T-I/SN

24AA512T-I/SN

24FC512T-I/SN

24FC512T-I/SNC21

24FC512T-I/SNC79

24LC512T-E/SN

24AA256-E/SN

24FC256-E/SN

24AA256-I/SN104

24AA256T-I/SN104

24AA256T-I/SN105

24LC256T-I/SNRVF

24AA256T-E/SN

24FC256T-E/SN

24AA256UID-I/SN

24AA256UIDT-I/SN

MCP6N11-001E/SN

MCP6N11T-001E/SN

MCP6N11-002E/SN

MCP6N11T-002E/SN

MCP6N11-005E/SN

MCP6N11T-005E/SN

MCP6N11-010E/SN

MCP6N11T-010E/SN

MCP6N11-100E/SN

MCP6N11T-100E/SN

MCP4801-E/SN

MCP4811-E/SN

MCP4821-E/SN

MCP4901-E/SN

MCP4911-E/SN

MCP4921-E/SN

MCP4801T-E/SN

MCP4811T-E/SN

MCP4821T-E/SN

MCP4901T-E/SN

MCP4911T-E/SN

MCP4921T-E/SN

PIC12F752-E/SN

PIC12F752-I/SN

PIC12F752T-I/SN024

PIC12F752T-I/SN

PIC12HV752-E/SN

PIC12HV752-I/SN

JAON-04TMOL584 - CCB 4539 Cancellation Notice: For the qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site

MCP6SZZT-I/SN

MCP6272-E/SN

MCP6282-E/SN

MCP6292-E/SN

MCP6272T-E/SN

MCP6282T-E/SN

MCP6292T-E/SN

MCP6L92T-E/SN

24LC02B/SN

24AA02/SN

24LC02B-E/SN

24LC02B-I/SN

24AA02-I/SN

24LC02BT/SN

24LC02BT/SNA31

24AA02T/SN

24LC02BT-I/SN

24AA02T-I/SN

MCP6032T-E/SN

MCP6032T-E/SNEIE

MCP6051-E/SN

MCP6061-E/SN

MCP6071-E/SN

MCP6051T-E/SN

MCP6061T-E/SN

MCP6071T-E/SN

MCP6052-E/SN

MCP6062-E/SN

24LCS21AT/SN

24LC21AT/SN

24LC21T/SN

24LC21AT-I/SN100

24LCS21AT-I/SN

24LC21AT-I/SN

24LC21T-I/SN

24LCS22A-I/SN

24LC22A-I/SN

24LCS22AT-I/SN

24LC22AT-I/SN

MCP606-I/SN

MCP608-I/SN

MCP606T-I/SN

MCP608T-I/SN

PIC12C508A-04/SN208

PIC12LC508A-04/SN

PIC12C508A-04/SN

PIC12C508A-04E/SN

PIC12LC508A-04I/SN

PIC12C508A-04I/SN

JAON-04TMOL584 - CCB 4539 Cancellation Notice: For the qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site

PIC12C508AT-04/SN208

PIC12C508AT-04/SN

PIC12C508AT-04I/SN077

PIC12C508AT-04I/SN123

PIC12LC508AT-04I/SN167

PIC12LC508AT-04I/SN168

PIC12C508AT-04I/SN221

PIC12C508AT-04I/SN231

PIC12C508AT-04I/SN

PIC12LC509A-04/SN

PIC12C509A-04/SN

PIC12C509A-04E/SN

PIC12LC509A-04I/SN

PIC12C509A-04I/SN

PIC12C509A-04I/SNC09

PIC12C509AT-04/SN

PIC12LC509AT-04I/SNG063

PIC12LC509AT-04I/SN126

PIC12LC509AT-04I/SN

PIC12C509AT-04E/SN

MCP130-270I/SN

MCP130-300I/SN

MCP130-315I/SN

MCP130-450I/SN

MCP130-460I/SN

MCP130-475I/SN

MCP130-485I/SN

MCP130T-270I/SN

MCP130T-300I/SN

MCP130T-315I/SN

MCP130T-450I/SN

MCP130T-460I/SN

MCP130T-475I/SN

MCP130T-485I/SN

MCP120-270I/SN

MCP120-300I/SN

MCP120-315I/SN

MCP120-450I/SN

MCP120-460I/SN

MCP120-475I/SN

MCP120-485I/SN

MCP120T-270I/SN

MCP120T-300I/SN

MCP120T-315I/SN

MCP120T-450I/SN

MCP120T-460I/SN

MCP120T-475I/SN

MCP120T-485I/SN

MCP607-I/SN

JAON-04TMOL584 - CCB 4539 Cancellation Notice: For the qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site

MCP607T-I/SN

MCP607T-I/SNA21

MCP6021-E/SN

MCP6023-E/SN

MCP6021-I/SN

MCP6023-I/SN

MCP6021T-I/SN

MCP6023T-I/SN

MCP6021T-E/SN

MCP6023T-E/SN

MCP6022-E/SN

MCP6022-I/SN

MCP6022T-I/SN

MCP6022T-E/SN

MCP616-I/SN

MCP618-I/SN

MCP616T-I/SN

MCP618T-I/SN

MCP617-I/SN

MCP617T-I/SN

MCP6541-E/SN

MCP6543-E/SN

MCP6541-I/SN

MCP6543-I/SN

93AA46B-I/SN

93AA46BX-I/SN

93AA46BT-I/SN

93AA46BXT-I/SN

93LC46BT-E/SN

93LC46BXT-E/SN

93C46B/SN

93C46BX/SN

93C46B-E/SN

93C46BX-E/SN

93C46B-I/SN

93C46BX-I/SN

93C46BT/SN

93C46BXT/SN

93C46BT-I/SN

93C46BXT-I/SN

93C46BT-E/SN

93C46BXT-E/SN

93C46A-E/SN

93C46AX-E/SN

93C46A-I/SN

93C46AX-I/SN

93C46AT-I/SN

93C46AXT-I/SN

93C46AT-E/SN

JAON-04TMOL584 - CCB 4539 Cancellation Notice: For the qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site

93C46AXI-E/SN

93LC46C-E/SN

93LC46CX-E/SN

93LC46C-I/SN

93LC46CX-I/SN

93AA46C-I/SN

93AA46CX-I/SN

93LC46CT-I/SN

93LC46CXT-I/SN

MCP6072-E/SN

MCP6052T-E/SN

MCP6062T-E/SN

MCP6072T-E/SN

MCP41010-E/SN

MCP41010-I/SN

MCP41010T-I/SN

MCP41010T-E/SN

MCP601-E/SN

MCP603-E/SN

MCP601-I/SN

MCP603-I/SN

MCP601T-I/SN

MCP603T-I/SN

MCP601T-E/SN

MCP603T-E/SN

MCP6L1T-E/SN

MCP3201-BI/SN

MCP3201-CI/SN

MCP3201T-BI/SN

MCP3201T-CI/SN

MCP3202-BI/SN

MCP3202-CI/SN

MCP3202T-BI/SN

MCP3202T-CI/SN

MCP3001-I/SN

MCP3001T-I/SN

MCP3002-I/SN

MCP3002T-I/SN

MCP602-E/SN

MCP602-I/SN

PIC12LF1840-E/SN

MTCH112-I/SN

PIC12LF1840-I/SN

MTCH112T-I/SN

PIC12LF1840T-I/SN

PIC12LF1840T-E/SN

PIC12F1501-E/SN047

PIC12F1501-E/SN048

PIC12F1501-E/SN

JAON-04TMOL584 - CCB 4539 Cancellation Notice: For the qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site

PIC12F1501-I/SN

PIC12F1501-I/SNH3A

PIC12F1501T-I/SN027

PIC12F1501T-I/SN

PIC12F1501T-I/SNH1A

PIC12F1501T-I/SNH2A

PIC12F1501T-I/SNH3A

PIC12F1501T-I/SNL1A

PIC12F1501T-I/SNL2A

PIC12F1501T-I/SNL3A

PIC12F1501T-I/SNL4A

PIC12F1501T-E/SN022

PIC12F1501T-E/SN032

PIC12F1501T-E/SN033

PIC12F1501T-E/SN034

PIC12F1501T-E/SN035

PIC12F1501T-E/SN047

PIC12F1501T-E/SN048

PIC12F1501T-E/SN052

PIC12F1501T-E/SN

PIC12LF1501-E/SN

PIC12LF1501-I/SN

PIC12LF1501T-I/SN023

PIC12LF1501T-I/SN024

PIC12LF1501T-I/SN

PIC12LF1501T-E/SN

PIC12F1612-E/SN

PIC12F1612-I/SN

PIC12LF1612-E/SN

PIC12LF1612-I/SN

PIC12LF1612T-I/SN

PIC12F1571-E/SN

PIC12F1572-E/SN

PIC12F1571-I/SN030

PIC12F1571-I/SN032

PIC12F1571-I/SN035

PIC12F1571-I/SN038

PIC12F1571-I/SN057

PIC12F1571-I/SN063

PIC12F1571-I/SN

PIC12F1572-I/SN

PIC12F1572T-I/SN020

PIC12F1571T-I/SN030

PIC12F1572T-I/SN034

PIC12F1571T-I/SN038

PIC12F1571T-I/SN042

PIC12F1572T-I/SN048

PIC12F1572T-I/SN052

PIC12F1571T-I/SN056

JAON-04TMOL584 - CCB 4539 Cancellation Notice: For the qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site

PIC12F1571T-I/SN057

PIC12F1571T-I/SN063

PIC12F1572T-I/SN064

PIC12F1571T-I/SN

PIC12F1572T-I/SN

PIC12F1572T-E/SN048

PIC12F1571T-E/SN

PIC12F1572T-E/SN

PIC12LF1571-E/SN

PIC12LF1572-E/SN

PIC12LF1572-I/SN033

PIC12LF1571-I/SN

PIC12LF1572-I/SN

PIC12LF1571T-I/SN026

PIC12LF1571T-I/SN028

PIC12LF1571T-I/SN029

PIC12LF1571T-I/SN031

PIC12LF1572T-I/SN033

PIC12LF1571T-I/SN

PIC12LF1572T-I/SN

PIC12LF1572T-E/SN

MCP2551-E/SN

MCP2551-I/SN

MCP2551T-I/SN

MCP2551T-E/SN

MCP2003-E/SN

MCP2003T-E/SN

MCP2004-E/SN

MCP2004T-E/SN

MCP2003A-E/SN

MCP2003AT-E/SN

MCP2004A-E/SN

MCP2004AT-E/SN

MCP2025-500E/SN

MCP2025T-500E/SN

MCP2025-330E/SN

MCP2025T-330E/SN

RE46C100S8F

RE46C101S8F

RE46C101S8TF

RE46C100S8TF

RE46C108S8F

RE46C108S8TF

RE46C317S8F

RE46C317S8TF

RE46C318S8F

RE46C318S8TF

TC1044SCOA

TC7660SCOA

JAON-04TMOL584 - CCB 4539 Cancellation Notice: For the qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site

TC7662BCOA

TC7660SVOA

TC1044SEOA

TC7660SEOA

TC7662BEOA

TC1044SEOA713

TC7660SEOA713

TC7660SEOA713BAA

TC7660SEOA713BAB

TC7662BEOA713

TC1044SCOA713

TC7660SCOA713

TC7662BCOA713

TC7660SVOA713

TC7660SEOA723

TC7660COA

TC7660EOA

TC7660MEOA

TC7660EOA713

TC7660MEOA713

TC7660COA713

TC7660EOA723

TC622COA

TC622VOA

TC622EOA

TC622EOA713

TC622COA713

TC622VOA713

MCP6541T-I/SN

MCP6543T-I/SN

MCP6541T-E/SN

MCP6543T-E/SN

MCP6542-E/SN

MCP6542-I/SN

MCP6542T-I/SN

MCP6542T-E/SN